

Description

The SX65N06D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 60V$ $I_D = 65A$

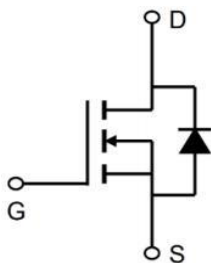
$R_{DS(ON)} < 13m\Omega$ @ $V_{GS}=10V$

Application

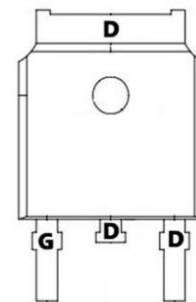
Battery protection

Load switch

Uninterruptible power supply



TO-252-3L



Absolute Maximum Ratings@ $T_J=25^\circ C$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, V_{GS} @ 10V ¹	65	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, V_{GS} @ 10V ¹	54	A
I_{DM}	Pulsed Drain Current ²	190	A
E_{AS}	Single Pulse Avalanche Energy ³	195	mJ
I_{AS}	Avalanche Current	38	A
$P_D@T_C=25^\circ C$	Total Power Dissipation ⁴	52	W
$P_D@T_A=25^\circ C$	Total Power Dissipation ⁴	1.1	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	2.4	$^\circ C/W$

Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=250\mu A$	60	65	---	V
$\Delta BVDSS/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1mA$	---	0.052	---	V/ $^{\circ}\text{C}$
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=10V$, $I_D=30A$	---	9.0	13	m Ω
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=4.5V$, $I_D=20A$	---	12	15	m Ω
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu A$	1.2	2.0	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.76	---	mV/ $^{\circ}\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=60V$, $V_{GS}=0V$, $T_J=25^{\circ}\text{C}$	---	---	1	uA
		$V_{DS}=60V$, $V_{GS}=0V$, $T_J=55^{\circ}\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=5V$, $I_D=30A$	---	42	---	S
Rg	Gate Resistance	$V_{DS}=0V$, $V_{GS}=0V$, $f=1MHz$	---	3.6	---	Ω
Qg	Total Gate Charge (4.5V)	$V_{DS}=48V$, $V_{GS}=10V$, $I_D=30A$	---	28.7	---	nC
Qgs	Gate-Source Charge		---	10.5	---	
Qgd	Gate-Drain Charge		---	9.9	---	
Td(on)	Turn-On Delay Time	$V_{DD}=30V$, $V_{GS}=10V$, $R_G=4.7\Omega$, $I_D=15A$	---	10.4	---	ns
Tr	Rise Time		---	9.2	---	
Td(off)	Turn-Off Delay Time		---	63	---	
Tf	Fall Time		---	4.8	---	
Ciss	Input Capacitance	$V_{DS}=30V$, $V_{GS}=0V$, $f=1MHz$	---	2603	---	pF
Coss	Output Capacitance		---	189	---	
Crss	Reverse Transfer Capacitance		---	173	---	
IS	Continuous Source Current ^{1,5}	$V_G=V_D=0V$, Force Current	---	---	80	A
ISM	Pulsed Source Current ^{2,5}		---	---	320	A
VSD	Diode Forward Voltage ²	$V_{GS}=0V$, $I_S=30A$, $T_J=25^{\circ}\text{C}$	---	---	1.4	V
trr	Reverse Recovery Time	$I_F=30A$, $dI/dt=100A/\mu s$, $T_J=25^{\circ}\text{C}$	---	18	---	nS
Qrr	Reverse Recovery Charge		---	14	---	nC

Note :

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is $V_{DD}=48V$, $V_{GS}=10V$, $L=0.1mH$, $I_{AS}=27.9A$
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

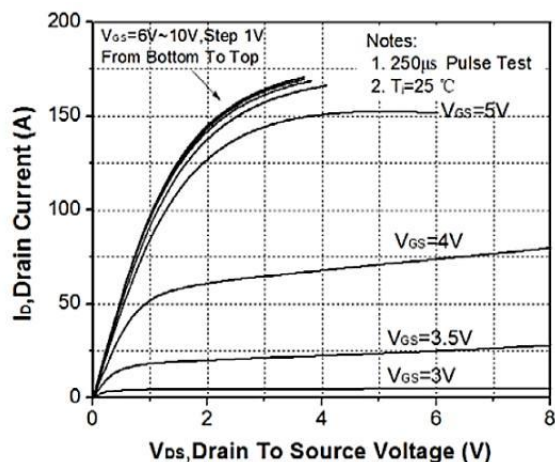


Figure1. On-state characteristics

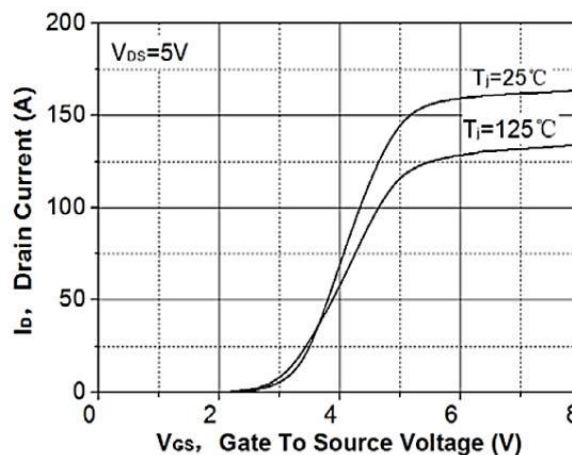


Figure2. Transfer Characteristics

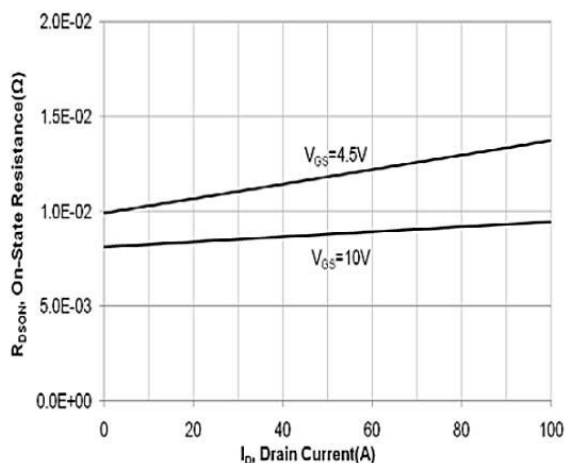


Figure3. On-resistance variation vs. drain current and gate voltage

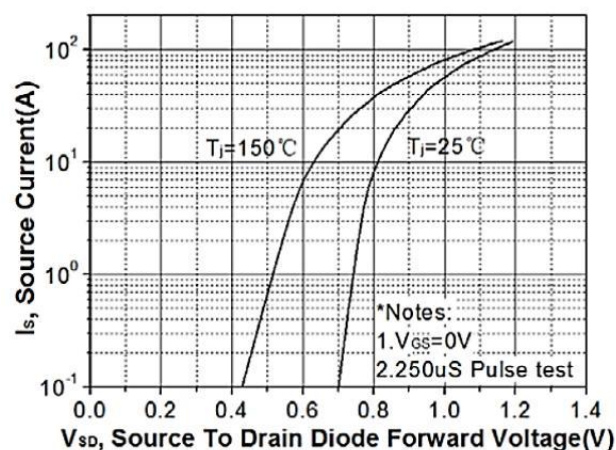


Figure4. On-state current vs. diode forward voltage

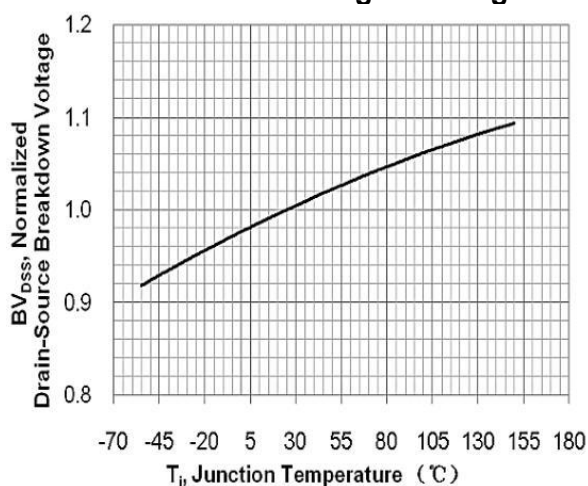


Figure5 . Breakdown voltage variation vs. junction temperature

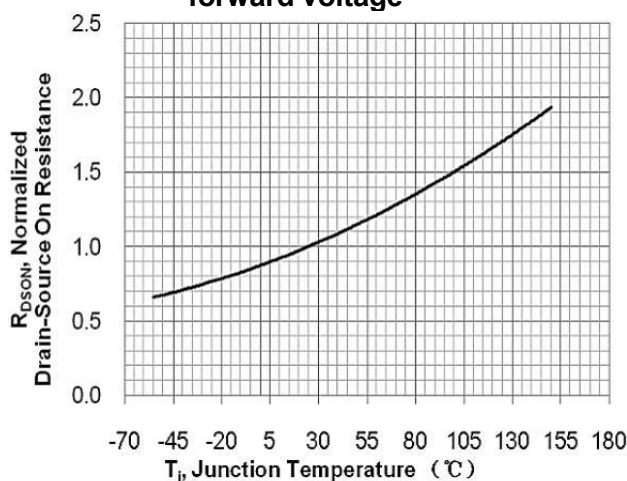


Figure 6. On-resistance variation vs. junction temperature

Typical Characteristics

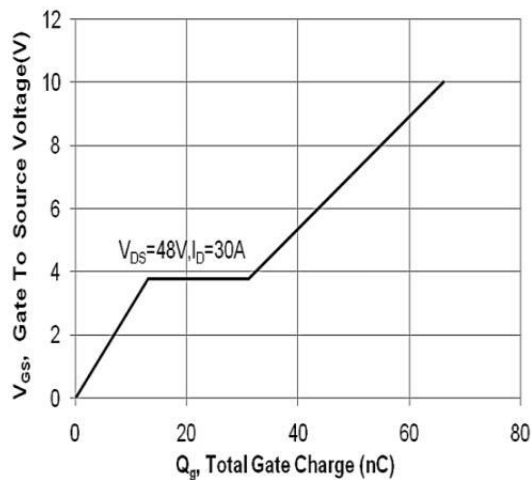


Figure7. Gate charge characteristics

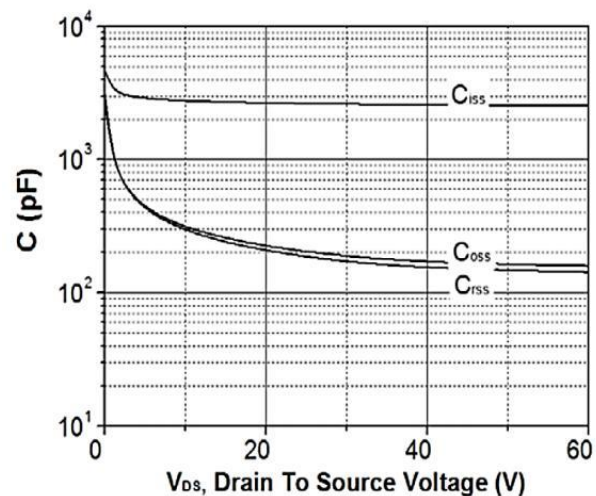


Figure8. Capacitance Characteristics

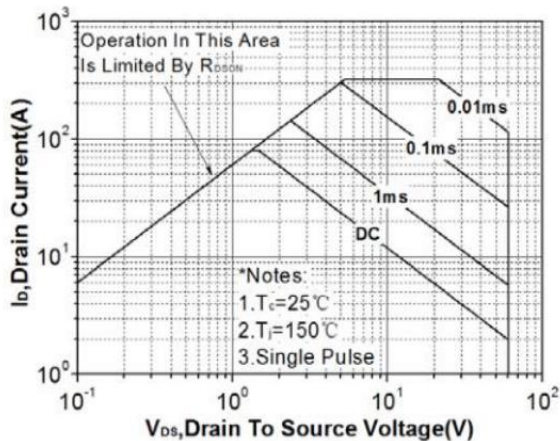


Figure9. Maximum safe operating area

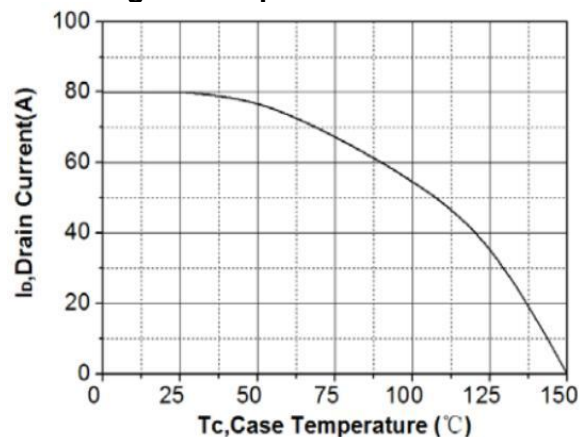


Figure10. Maximum drain current

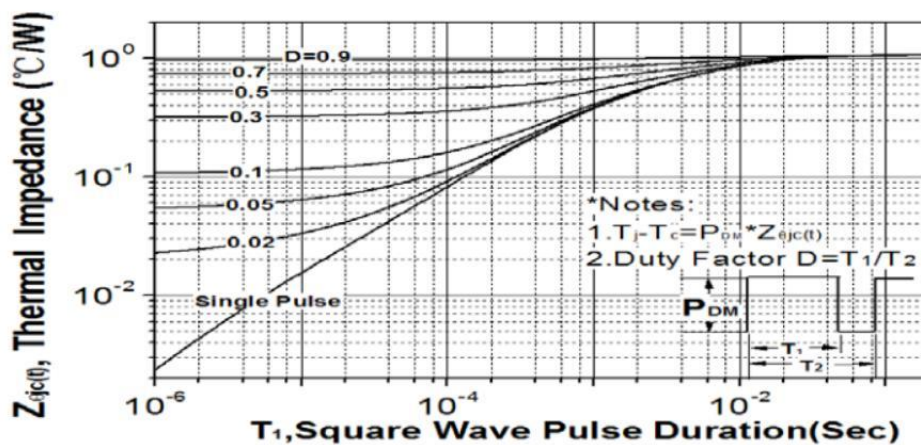
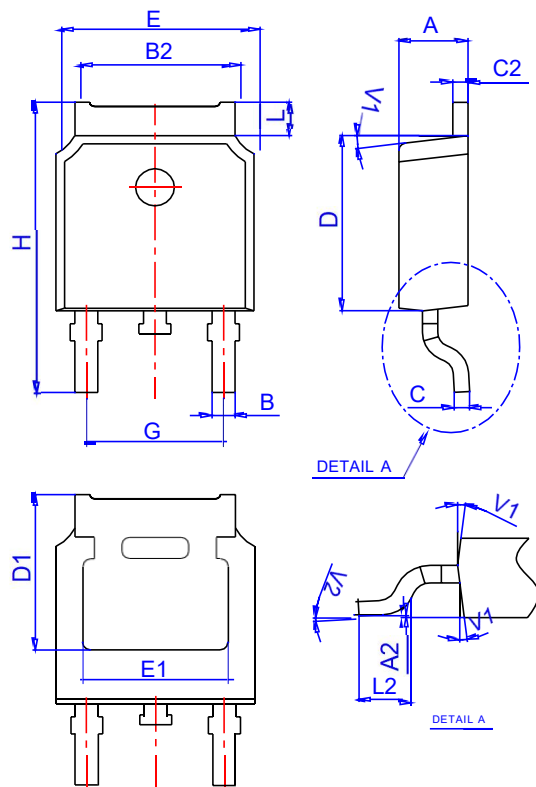


Figure11. Transient thermal response curve vs. case temperature

Package Mechanical Data: TO-252-3L



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	TO-252-3L		2500